



Material Content Data Sheet



Sales Product Name		BSS316N H6327		Issued		26. August 2018		
MA#		MA001627312						
Package		PG-SOT23-3-5		Weight*		9.36 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.02		221	
	noble metal	gold	7440-57-5	0.008	0.09		857	
	inorganic material	silicon	7440-21-3	0.122	1.31	1.42	13070	14148
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		322	
	non noble metal	chromium	7440-47-3	0.009	0.10		966	
	non noble metal	copper	7440-50-8	3.000	32.06	32.20	320572	321924
wire	non noble metal	copper	7440-50-8	0.044	0.47	0.47	4742	4742
encapsulation	organic material	carbon black	1333-86-4	0.057	0.61		6128	
	plastics	epoxy resin	-	1.233	13.18		131754	
	inorganic material	silicondioxide	60676-86-0	4.445	47.48	61.27	474928	612810
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	15988	15988
plating	noble metal	silver	7440-22-4	0.284	3.04	3.04	30388	30388
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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